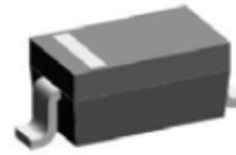


**Small Signal Product**

**200mW, Low VF SMD Schottky Barrier Diode**

**FEATURES**

- Low power loss, high current capability, low  $V_F$
- Surface device type mounting
- Moisture sensitivity level 1
- Matte Tin(Sn) lead finish with Nickel(Ni) underplate
- Pb free version and ROHS compliant
- Green compound (Halogen free) with suffix "G" on packing code and prefix "G" on date code



**SOD-323**



**MECHANICAL DATA**

**Case :** SOD-323 small outline plastic package

**Terminals :** Matte tin plated, lead free, solderable per MIL-STD-202, method 208 guaranteed

High temperature soldering guaranteed : 260°C/10s

**Polarity :** Indicated by cathode band

**Weight :** 0.004grams (approximately)

**Marking Code :** 5

MAXIMUM RATINGS AND ELECTRICAL CHARACTERISTICS ( $T_A=25^\circ\text{C}$ unless otherwise noted)			
PARAMETER	SYMBOL	VALUE	UNITS
Power dissipation	$P_D$	200	mW
Reverse voltage	$V_R$	30	V
Repetitive peak reverse voltage	$V_{RRM}$	40	V
Mean Forward Current @ 25° C ( Lead Temperature )	$I_o$	30	mA
Non-repetitive peak forward surge current (Note 1)	$I_{FSM}$	0.2	A
Thermal resistance (Junction to Ambient) (Note 2)	$R_{\theta JA}$	500	°C/W
Junction and storage temperature range	$T_J, T_{STG}$	-45 to + 125	°C

PARAMETER	SYMBOL	MIN	MAX	UNITS
Forward voltage $I_F=1.0\text{mA}$	$V_F$	-	0.37	V
Reverse leakage current $V_R=30\text{V}$	$I_R$	-	0.5	$\mu\text{A}$
Junction capacitance $V_R=1, f=1.0\text{MHz}$	$C_J$	2		pF

Notes : 1. Test Condition: 8.3ms single half sine-wave superimposed on rated load (JEDEC method)

Notes : 2. Valid provided that terminals are kept at ambient temperature

**Small Signal Product**

ORDERING INFORMATION					
PART NO.	PACKING CODE	GREEN COMPOUND CODE	PACKAGE	PACKING	MANUFACTURE CODE
RB751V-40	RR	RRG	SOD-323	3K / 7" Reel	(Note)

Note: Manufacture special control, if empty means no special control requirement.

EXAMPLE					
PREFERRED P/N	PART NO.	PACKING CODE	GREEN COMPOUND CODE	MANUFACTURE CODE	DESCRIPTION
RB751V-40	RB751V-40	RR	G	D0	Green compound

**RATINGS AND CHARACTERISTICS CURVES**

(TA=25°C unless otherwise noted)

Fig. 1 Typical Forward Characteristics

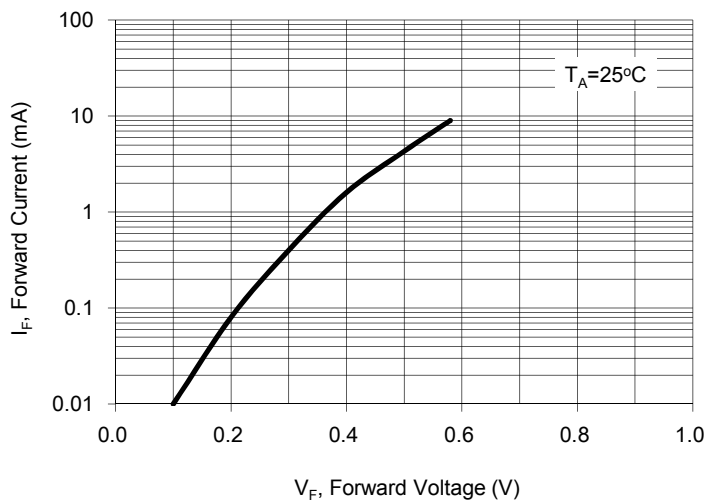


Fig. 2 Forward Current Derating Curve

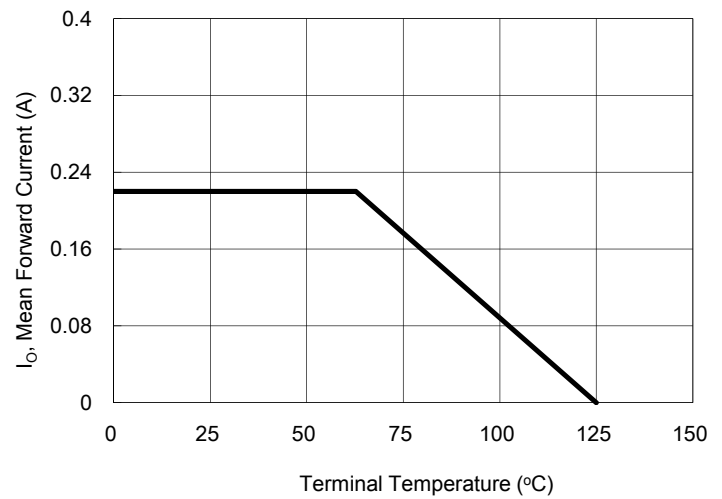


Fig. 3 Admissible Power Dissipation Curve

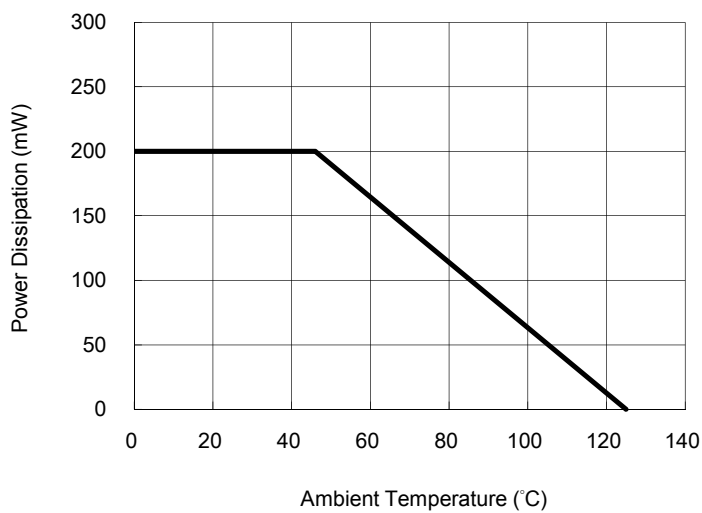
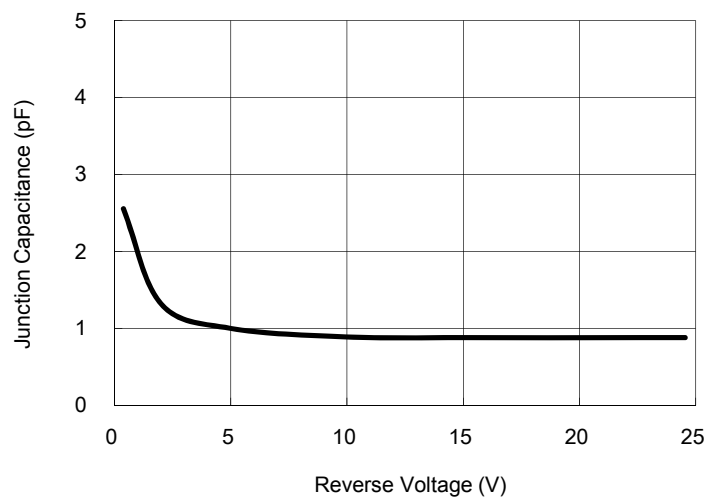
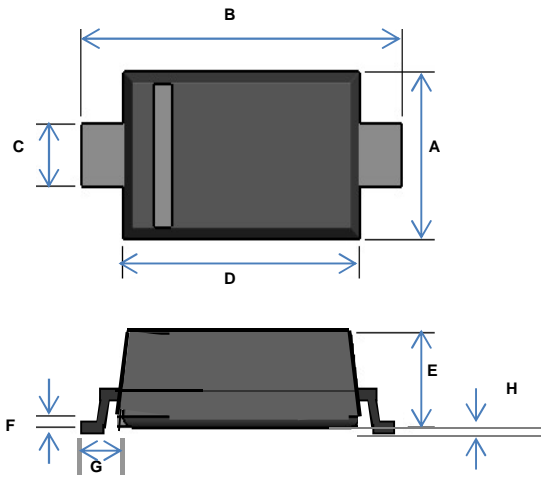


Fig. 4 Typical Junction Capacitance



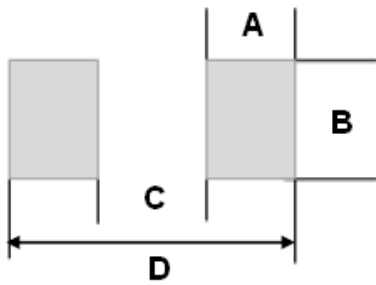
**Small Signal Product**

**DIMENSIONS**



DIM.	Unit(mm)		Unit(inch)	
	Min	Max	Min	Max
A	1.150	1.400	0.045	0.055
B	2.300	2.700	0.091	0.106
C	0.250	0.450	0.010	0.018
D	1.600	1.800	0.063	0.071
E	0.800	1.000	0.031	0.039
F	0.050	0.177	0.002	0.007
G	0.475 REF		0.019 REF	
H	-	0.100	-	0.004

**SUGGESTED PAD LAYOUT**



DIM.	Unit(mm)	Unit(inch)
	Typ.	Typ.
A	0.63	0.025
B	0.83	0.033
C	1.60	0.063
D	2.86	0.113